



Material Content Data Sheet



Sales Product Name		BTS5090-1EJA		Issued		1. August 2018		
MA#		MA002296628						
Package		PG-DSO-8-43		Weight*		85.70 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.775	2.07	2.07	20715	20715
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		110	
	non noble metal	zinc	7440-66-6	0.038	0.04		439	
	non noble metal	iron	7439-89-6	0.752	0.88		8773	
wire	non noble metal	copper	7440-50-8	30.529	35.62	36.55	356227	365549
	non noble metal	copper	7440-50-8	0.361	0.42	0.42	4209	4209
	encapsulation	organic material	carbon black	1333-86-4	0.097	0.11		1132
encapsulation	plastics	epoxy resin	-	4.463	5.21		52072	
	inorganic material	silicondioxide	60676-86-0	43.946	51.29	56.61	512792	565996
leadfinish	non noble metal	tin	7440-31-5	1.628	1.90	1.90	18993	18993
plating	noble metal	silver	7440-22-4	1.452	1.69	1.69	16943	16943
glue	plastics	epoxy resin	-	0.114	0.13		1329	
	noble metal	silver	7440-22-4	0.537	0.63	0.76	6266	7595
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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